

Compound Semiconductor Materials North America TC Chapter

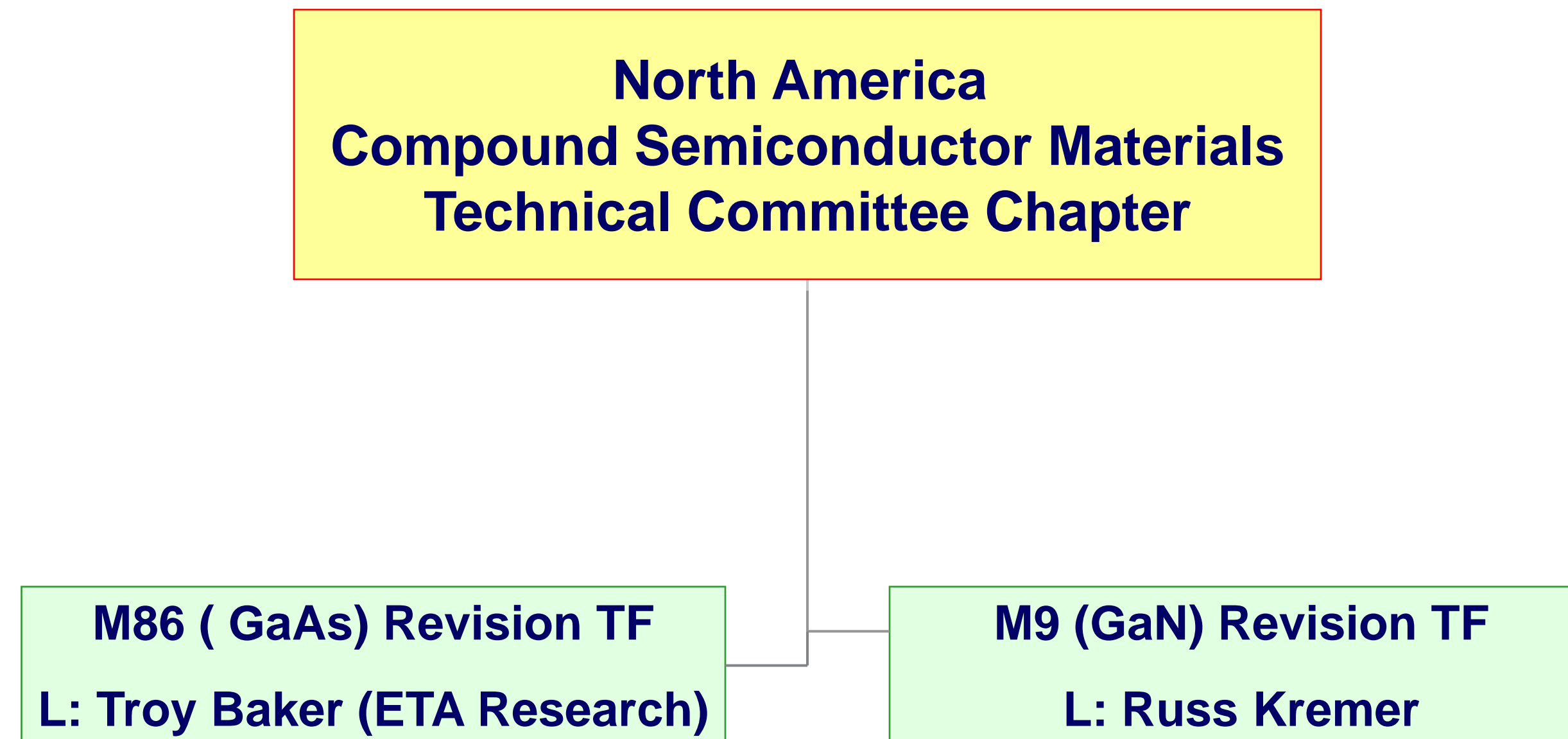
Liaison Report

November 10, 2021

Leadership

- Committee Co-chairs
 - Russ Kremer / Consultant
 - Jim Oliver / Consultant

Current Committee Structure



Meeting Information

- Last meeting
 - Nov 10, 2021
 - 9:00 AM – 11:00 AM Pacific
 - Online
- Next meeting
 - Jun 15, 2022

Ballot Review

- Doc. 6805, Revision of SEMI M9.5 with title change from “Specification for Round 100mm Polished Monocrystalline Gallium Arsenide Wafers for Electronic Device Applications” to “Specification for Round 100mm Polished Monocrystalline Gallium Arsenide Wafers.”
 - Passed as balloted
- Doc. 6818, Withdrawal of SEMI M9.1-0813 Specification For Round 50.8 mm Polished Monocrystalline Gallium Arsenide Wafers For Electronic Device Applications
 - Passed as balloted
- Doc. 6819, Withdrawal of SEMI M9.6-0813 Specification For Round 125 mm Diameter Polished Monocrystalline Gallium Arsenide Wafers
 - Passed as balloted
- Doc. 6806, Revision of SEMI M86-0915 Specification for Polished Monocrystalline C-Plane Gallium Nitride Wafers
 - Passed with editorial change

Task Force Updates



- M86 (GaN) Revision TF
 - Doc. 6806, Revision of M86, Specification for Polished Monocrystalline c-Plane Gallium Nitride Wafers (Subject: To revise 1-4 inches diameter)
 - Passed and forwarded to ISC for procedural review

5 year review

- SEMI M65-0816, Specification for Sapphire Substrates to use for Compound Semiconductor Epitaxial Wafers
 - Checking with sapphire substrate manufacturers for input.

Thank You!

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